Product Roadmap

2026 Q1

ARK-I 2I640PW+ DM003

ROCK 2I130HW

SealPro - 2I130HW

SealPro - 3I140HW

TERA M12

HAWK 3I130TW

RUGGED EMBEDDED SYSTEM

Harsh Environments and Mission-Critical Application

MIL-STD-810G Certified

EXTREME TEMP

Anti Vibration

SHOCK &VIBRATION RESISTANT

Lex SYSTEM®

Contents

- LEX System Features & Advantages
- Embedded Solution Overview
- Embedded Solution Case Study
- Product Highlights
- Product Development Timeline
- Product long term supply
- Contact Information

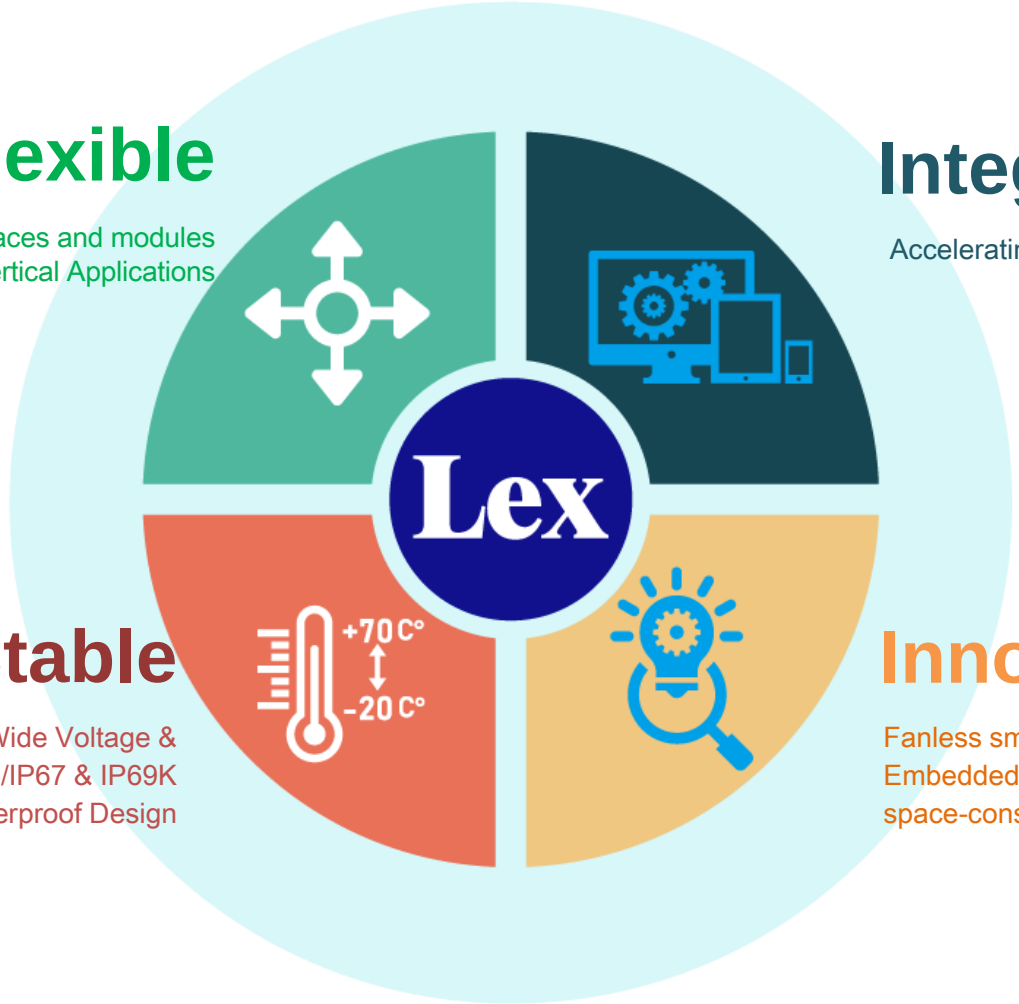
Features & Advantages

Flexible

Diverse Expansion interfaces and modules
for various Vertical Applications

Integrated

Accelerating Customer Development Speed
for Cross-Platform products



Stable

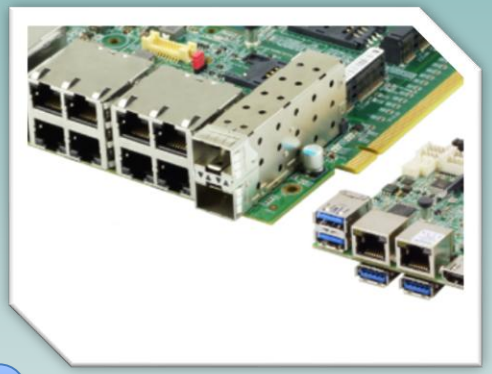
Wide Temperature, Wide Voltage &
Shock Resistance, IP66/IP67 & IP69K
Waterproof Design

Innovation

Fanless small Form Factor
Embedded tailored products or
space-constrained solutions

LEX SYSTEM – Embedded Solution

LEX offers design and manufacturing of industrial motherboards, industrial computers, expansion boards, and customized industrial computers, including edge computing systems and AI intelligent application platforms. Our in-house developed products cover four major categories:



1 Embedded IPC Board

- Single Board Computer
- CPU board
- Computer On Module
- UPS board
- ARM-based SBC

2 Customized Motherboard & Chassis

Innovating Research & Integration Services for Global OEM/ODM and System Integrators

• Applications

- Smart Manufacturing / Machine Vision
- AI / Visual Analytics
- Smart Healthcare/ AI Medical Imaging
- IoT / IIoT
- Smart Transportation & Railways
- Maritime Shipping & Navigation
- Defense / Military Robust Computers
- Edge Computing Edge Gateway Control
- Networking/ Communication Equipment

LEX SYSTEM – Embedded Solution

3 Fanless Rugged Panel PC,
Fanless Embedded Systems, Servers

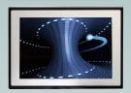
4 Expansion Boards/Cards &
Related Accessories

Fanless Rugged Panel PC

•SUPER **series** (7”/10.1”/10.4”/15”)

•VITA **series** (10.1”/15”/21.5”/23.8”)

•Slim series (8.4”/10.2”/15.1”/17”)



•SHARK IP66/67 **waterproof** (10.1”/13.3”)

•STAR IP66/67 **waterproof** (10.4”/12.1”15.1”)

•**Stainless** IP66/IP67/IP69K **waterproof**

(10.4”/15.1”/19”)

Fanless Embedded System

•Rugged /Waterproof System

•In-vehicle System

•DIN Rail System

•1U server

•AI image Analysis & Machine Vision

•Ultra Compact / Compact System

•High-Speed Ethernet Network Card / PoE / Fiber Card

•4G / 5G / WiFi / Bluetooth Module

•Video Capture Car

•USB / SIM / COM / Display Conversion Card

• M.2 / eIO Expansion Card

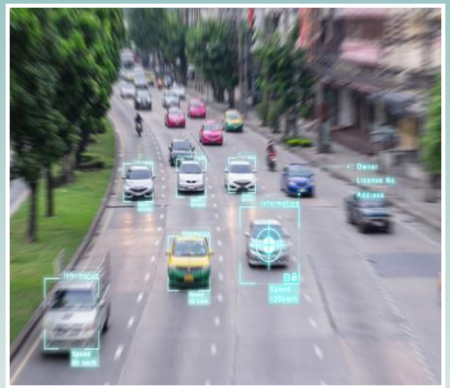
•Storage Card

•Digital IO Card

•Carriers and Converter Boards

•Power Boards and Charger Modules

Embedded Solution– Case Study



Spain
Intelligent Transportation
Surveillance System

China
Highway ETC smarting
billing system

Germany
3D Surgery Navigation

China
Servortronix EtherCAT
Robot Motion Control

Embedded Solution– Case Study

Kiosk-Self Service
Harsh outdoor Panel PC
for Winter Olympics

Video Analysis
Metro Real-time
Surveillance System

Poland
Railway in-train
communication

Netherlands
Fleet management

2026 Q1 Product Highlights

3I160DW-3.5” SBC

Intel® Core™ Ultra CPU
(Panther Lake-H)
DP, HDMI ®, LVDS
2 x DDR5 SODIMM Max 64GB
5 x Intel 2.5 GbE, 3 x USB 3.2, 3 x USB 2.0
3 x M.2 ,1 x Nano SIM , HD Audio
4 x COM, 4DI / 4DO

2I140D-2.5” SBC

Intel® Core™ Ultra CPU
(Meteor Lake-U/H) (Arrow Lake-U/H)
DP, HDMI ®, LVDS /DP
2 x DDR5 SODIMM Max 64GB
3 x Intel 2.5 GbE, 4 x USB 3.2, 3 x USB 2.0
3 x M.2 ,1 x Nano SIM, HD Audio
4 x COM, 4DI / 4DO ,2 X MIPI-CSI

3I140HW-3.5” SBC

Intel® Core™ Ultra CPU
(Meteor Lake-U/H) (Arrow Lake-U/H)
DP, HDMI ®, LVDS /DP
2 x DDR5 SODIMM Max 64GB
3 x Intel 2.5 GbE, 4 x USB 3.2, 3 x USB 2.0
3 x M.2 ,1 x Nano SIM, HD Audio
4 x COM, 4DI / 4DO ,2 X MIPI-CSI

2I740DW-2.5” SBC

Intel® ATOM Amston Lake x7211/x7213 CPU
Onboard LPDDR5, 8GB / 16GB
DP,HDMI®
3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
2 x M.2 , 2 x COM, DC-IN 12V/24
115.4 x 84.5 mm

2I740CW-2.5” SBC

Intel® ATOM Amston Lake x7211/x7213 CPU
1 x SODIMM DDR5, Max 16GB
HDMI®, Type C , LVDS
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB 3.2 Type C,2 x M.2 , 1 x Nano SIM
2 x MIPI-CSI,4 x COM, 4DI/4DO
Wide Range DC-IN 9-36V
108x 102 mm

2I740AW-2.5” SBC

Intel® ATOM Amston Lake x7211/x7213 CPU
1 x SODIMM DDR5, Max 16GB
HDMI®, 1 x Intel 2.5 GbE, 4 x COM
4 x USB 3.2, 2 x USB 2.0
2 x M.2 , 1 x MINI SIM,
Wide Range DC-IN 9-24V
108 x 102 mm

2I740HW-2.5” SBC

Intel® ATOM Amston Lake x7211/x7213 CPU
Onboard LPDDR5, 8GB / 16GB
All wafer I/O

Product Highlights（Embedded IPC Board）

intel Core 13th Gen Raptor Lake

2I130HW-2.5” Plus SBC
2I130DW-2.5” Plus SBC
3I130DW-3.5” Plus SBC
3I130TW-161x150 mm SBC

intel Core 11th Gen Tiger Lake-UP3

2I110D-2.5” Plus SBC
2I110AW-2.5” Plus SBC
3I110HW/BW-3.5” Plus SBC

NVIDIA

2NOR01- 2.5” Plus carrier board
For Board for Edge AiI solution with NVIDIA® Jetson Orin™ Nano (Super)NX

ORIN-TW
Carrier Board for Railway solution with NVIDIA® Jetson Orin™ Nano(Super) / NX

2NOR02- compact carrier board
For Edge AiI solution with NVIDIA® Jetson Orin™ Nano / NX

2NOR03- compact carrier board
For Edge AiI solution with NVIDIA® Jetson Orin™ Nano / NX

intel Core 10th Gen Comet Lake-S

3I470DW-155 x150 mm SBC

intel Core 9 th Gen Coffee Lake-S
intel Core 8 th Gen Coffee Lake-S

CI370D-217 x 185 mm SBC
CI371D-217 x 223 mm SBC
3I370DW-155 x130 mm SBC

intel Core 8 th Gen Whiskey Lake-U

2I810D-2.5” Plus SBC
3I810DW-3.5” Plus SBC
3I810HW/BW-3.5” Plus SBC

intel Elkhart Lake
intel Atom inside

2I640PW-Compute on Module
2I640HL-2.5”Plus SBC with Hailo-8
2I640DW-2.5”Plus SBC
2I640CW-2.5”Plus SBC
2I640HW-2.5”Plus SBC
2I640SW-2.5”Plus SBC
3I640DW-3.5” SBC
3I640CW-3.5” SBC

NXP

2N8MP01- 2.5” Plus SBC

NXP-HAI02- -carrier board with Hailo AI chip
For Edge AiI solution with I.MX8M Plus CPU

NXP-HAI03 -carrier board with Hailo AI chip
For Edge AiI solution with I.MX8M Plus CPU

2026 Q1 Product Development timeline

Intel® Core™ Ultra CPU

CI870CW

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 64GB
Multiple Independent display:
1 x HDMI®, 1 x DP, 1 x eDP / LVDS, 1 x Type C
5 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
10 x COM, 8DI / 8DO, Audio
TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)

TWISTER(L)-CI870AW

TWISTER(L)-CI870CW

CI870AW

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 64GB
Multiple Independent display:
1 x HDMI®, 1 x DP,1 x Type C
2 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
4 x COM, 8DI / 8DO, TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)

1U Fanless-CI870AW

1U Fanless-CI870CW

2026 Q1 Product Development timeline

Intel® Core™ Ultra CPU

3I140DW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, 1 x DP, LVDS, 1 x Type C
5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
4 x COM, 2 x CANBus 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, I2S ,Wide Range DC IN+9~36V
Dimension: 150 x 155 mm

HAWK 3I140DW

3I140HW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, LVDS, 1 x Type C
3 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, High Speed Connector (PCIe x2)
4 x COM, 2 x MIPI-CSI, 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, Wide Range DC IN+9~36V
Dimension: 146 x 150 mm

SealPro 3I140HW

2026 Q1 Product Development timeline

13th Gen Intel® Core™ Raptor Lake-P/U

2I130HW

Intel® 13th Gen Raptor Lake-U/P CPU
1 x DDR5 SODIMM (Max. 32GB)
HDMI ®, eDP, LVDS
2 x Intel 2.5 GbE, 4 x USB 3.2
4 x USB 2.0 2 x COM, 4DI / 4DO,
HD Audio ,1 x Mini PCIe, 1 x M.2
108 x 102 mm

ROCK 2I130HW

SealPro 2I130HW

2I130DW

Intel® 13th Gen Raptor Lake-U CPU
1 x DDR5 SODIMM (Max. 32GB)
HDMI ®, eDP
4 x Intel 2.5 GbE, 3 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
2 x M.2 , 1 x Nano SIM
108 x 102 mm

FOX 2I130DW

ROCK 2I130DW

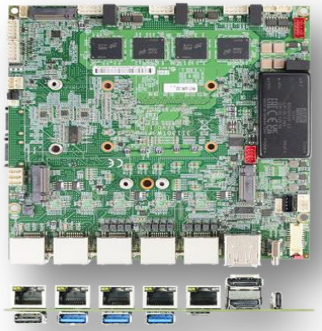
SKY 2 2I130DW

3I130DW

Intel® 13th Gen Raptor Lake-P / U CPU
2 x DDR5 SODIMM (Max. 64GB)
2 x HDMI ®,eDP , 1 x Type C DP ALT Mode
5 x Intel 2.5 GbE, 3 x USB 3.2, 5x USB 2.0
1 x Mini PCIe, 2 x M.2 ,1 x Nano SIM
2 x COM, 4DI / 4DO
146 x 110 mm

HAWK 3I130DW

SKY 3 3I130DW



3I130TW

Intel® 13th Gen Raptor Lake- U CPU
On-board LPDDR5 (16GB/32 GB)
HDMI ®,DP, eDP ,5 x Intel 2.5 GbE,
3 x USB 3.2, 3x USB 2.0, 3 x M.2 ,
1 x Nano SIM ,2 x ISO-COM, HD Audio
2 x ISO- CANBus, 4DI / 4DO , onboard NVMe
CPC –Ignition Delay on/off control
161 x 150 mm

EN50155

HAWK 3I130TW (M12)

Mobile Rack (Optional)

2026 Q1 Product Development timeline

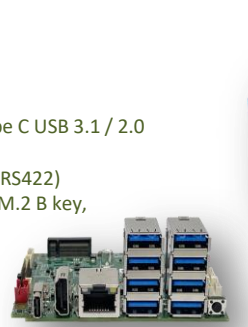
NVIDIA Jetson Orin Nano(Super)/ NX SOM Carrier Board

JETSON Orin™ NX | JETSON Orin™ Nano | NVIDIA

CPU Board:
NVIDIA Jetson NX: 8 / 16GB LPDDR5, 70 / 100 TOPs
NVIDIA Jetson Nano(Super): 4 / 8GB LPDDR5, 20 / 40 TOPs
AI Accelerator: NVIDIA® Jetson Orin™ Nano(Super) / Orin™ NX

2NOR02

1 x HDMI®, 1 x GbE
8 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
1 x RS232 (OEM to RS422)
1 x M.2 M key, 1 x M.2 B key,
URAT, I2S, 2 x I2C



FOX 2NOR02

ORIN-TW

1 x DP, 5 x GbE (1 + 4 x PoE)
1 x USB 3.1 Type C ; 2 x USB 3.1 Type A ; 1x USB 2.0
Mic-in / Line-out ; AMP 2W, 2 x SATA
2 x Isolated RS232 / RS422 / RS485, 1 x Isolated CANBus
1 x M.2 M key, 4 x M.2 B key, 1 x M.2 E Key, 1 x Nano SIM
2 x MIPI CSI, SPI, I²S, 3 x I²C,8DI / 8 DO,
ISO Wide Range +9~36V, CPC-Ignition on/off delay control

EN50155

HAWK ORIN-TW
M12 I/O / Mobile Rack (Optional)

2NOR03

1 x HDMI ®, 1 x GbE, 1 x 2.5GbE
2 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG)
1 x RS232 (OEM Option RS422)
1 x M.2 M key, 1 x M.2 B key
Support **8 X GMSL cameras**

FOX 2NOR03+GM04

2NOR01

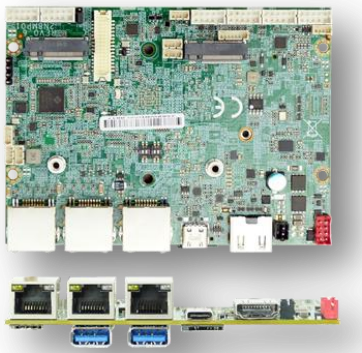
1 x HDMI®, , 2 x 2.5GbE, 1 x GbE
4 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
Mic-in / Line-out ; AMP 2W
2 x RS232 (Option RS422), 1 x CANBus
1 x M.2 M key 2 x M.2 B key, 1 x SIM, 4DI / 4DO
Internal wafer: SPI, I2S, I2C, USB 2.0

SKY 2 2NOR01

ROCK 2NOR01

2026 Q1 Product Development timeline

NXP i.MX8M Plus /ARM Cortex-A53



2N8MP01

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 + M7 CPU
LPDDR4, 4GB / 8GB
Independent display: 1 x HDMI ®, LVDS,
3 x GbE LAN, 2 x USB 3.0, 3 x USB 2.0
2 x COM, 3 x M.2, 1 x Nano SIM, 1 x Type C USB 3.0 (OTG)
4DI / 4DO,1 x MIPI (CSI),1 x CANBus
115.4 x 84.5 mm

NET-II 2N8MP01

Ultra Compact solution with Onboard Hailo-8™ AI processor

EMPOWERED BY HAILO

NXP-HAI02 / HAI03

NXP i.MX8M Plus (Quad core) ARM Cortex-A53 CPU
LPDDR4, 8GB (NEX-8MP),32-256GB eMMC 5.1 (NEX-8MP)
Mini HDMI ®, 1 x USB 3.0 Type C,1 x GbE(M12) or 2 x RJ45 ;
1 x USB 3.0 Type A, 1 x Micro SD,
M8 Connector: DC Power, LAN, DI/DO ,RS485
Wide Range DC-IN +9-24V
Dimension: 66W x 94D x 30.8H mm

NXP-HAI02 NXP-HAI03

With NEX-8MP computer on module

PALM-NEX001

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 CPU
LPDDR4, 8GB (NEX-8MP)
32GB eMMC 5.1 (NEX-8MP),
expandable to 256GB
HDMI ® ; 2 x GbE ; 2 x USB 3.0 / 2.0
1 x Micro SD, 1 x RS232, 1 x RS485
DC input : +5V
71.4W x 71.4D x 29.5H mm

MINI NXP-HAI02 MINI NXP-HAI03

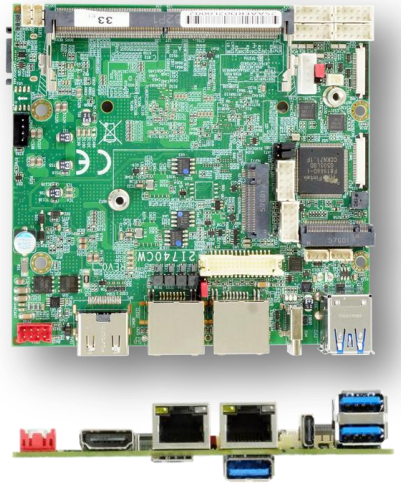
2026 Q1 Product Development timeline

Intel® Amston Lake ATOM x7000 series processor

2I740DW

Intel® ATOM Amston Lake x7000 series CPU
LPDDR5, 8GB / 16GB
HDMI® ,3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
2 x M.2 , 1 x Nano SIM, 2 x COM,
Wide Range DC-IN +9~24V
115.4 x 84.5 mm

NET-II 2I740DW



2I740CW

Intel® ATOM Amston Lake x7000 series CPU
1 x DDR5 SODIMM, Max. 16GB
HDMI®, Type C ALT, LVDS
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB3.2 Type C , 2 x MIPI-CSI, 4DI/4DO
2 x M.2 , 4 x COM, Wide Range DC-IN +9~36V
108 x 102 mm

LEX Sereies Pancel PC

2026 Q1 Product Development timeline

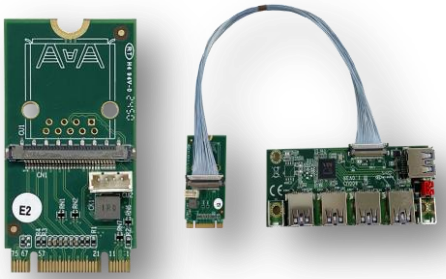
Expansion Card and Modules

CC107

USB to 4 x ISO RS232/422/485

M504B

Mini PCIe to 4* RS232/485/422
(F81504U)



CN073

M.2 B+M Key2242 connector board by
USB3.2 Type A / USB 3.2 SSL / PCIe

CU006

1 to 4 USB 3.0 HUB

CL210A

PCIe 2x or 4x to 4 port 2.5GbE

PW505

Isolation power board
with CPC-Ignition on/off control
1.5KVDC I/O isolation
PW505-36: 9–36V in, 12V out, max 60W
PW505-75: 18–75V in, 12V out, max 60W

ME225-A

Video Capture Card (from HDMI® device)
4K@30 RAW or
4K@60fps MJPEG

ME225-S

Video Capture Card (from HDMI® device)
High Speed Micro Coaxial Cable
4K@30 RAW or
4K@60fps MJPEG

RS806 –Riser card for 3I140DW
PCIex16 to PCIex8 (Meteor Lake-H series CPU

RS807 –Riser Card for 3I140DW
PCIex16 to PCIex1

LEX SYSTEM with Long-Term Supply

EOL Timeline	2028	2029	2030	2031	2032	2033	2034	2035	2036
Meteor Lake-U/H							Q1		
Raptor Lake-U						Q1			
Tiger Lake-UP3			Q3						
Comet Lake-S			Q2						
Whisky Lake-U						Q3			
Coffee Lake-S 9th							Q2		
Coffee Lake-S 8th						Q2			
Kaby Lake-U/S 7th					Q1				
Skylake-U/S 6th			Q3						
Elkhart Lake				Q1					
Apollo Lake				Q3					
Bay Trail	Q4								
Jetson Orin			Q1						
i.MX8M Plus									Q1

* Product life span in alignment with Intel's IOTG / NVIDIA modules Life cycle /NXP CPU longevity.

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